

10 9 8 7 6 5 4 3 2 1

F

F

E

E

D

D

C

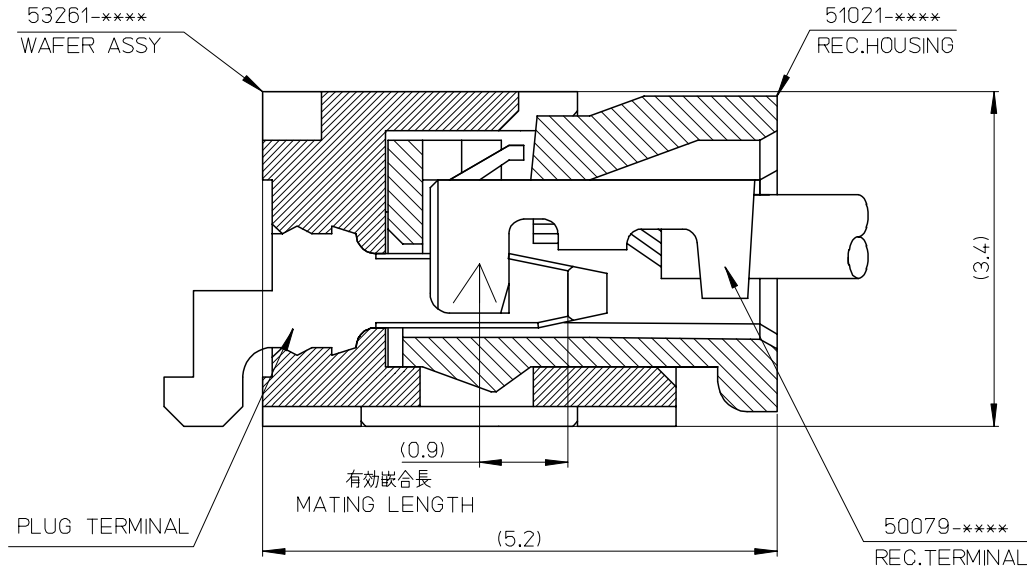
C

B

B

A

A

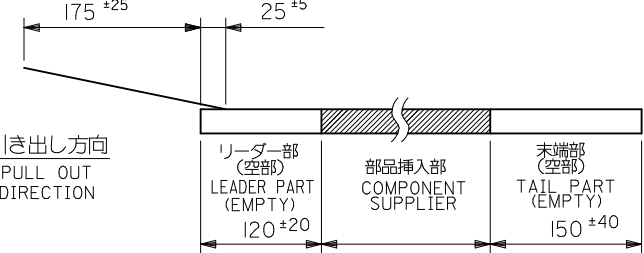


53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN: A0YAGI 2006/02/02 CHKD: YMAEDA 2006/02/03 APPR: NUKITA 2006/02/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY Y. A0YAGI	DATE 2006/01/30	TITLE 1.25 W-TO-B CONN. 51021,53261 MATING CROSS SECTION			
	10 OVER 30 UNDER	± ---	CHECKED BY Y. MAEDA	DATE 2006/01/30	APPROVED BY N. UKITA			
	30 OVER	± ---	APPROVED BY N. UKITA		DATE 2006/01/30	MOLEX INCORPORATED		
	ANGULAR	± --- °	MATERIAL NO.		DOCUMENT NO. SD-51021-002	SHEET NO. 1 OF 1		
0	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

注記
NOTES

- 53261-**-19 の詳細寸法については図面 SD-53261-024 を参照下さい。
RE DETAILED DIMENSIONS, SEE SD-53261-024
- 梱包数量: 1000個/リール
NUMBER OF CONNECTOR: 1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH
トップテープリーダー部 TOP TAPE LEADER PART
トップテープ未接着部 TOP TAPE NON-BONDED PART



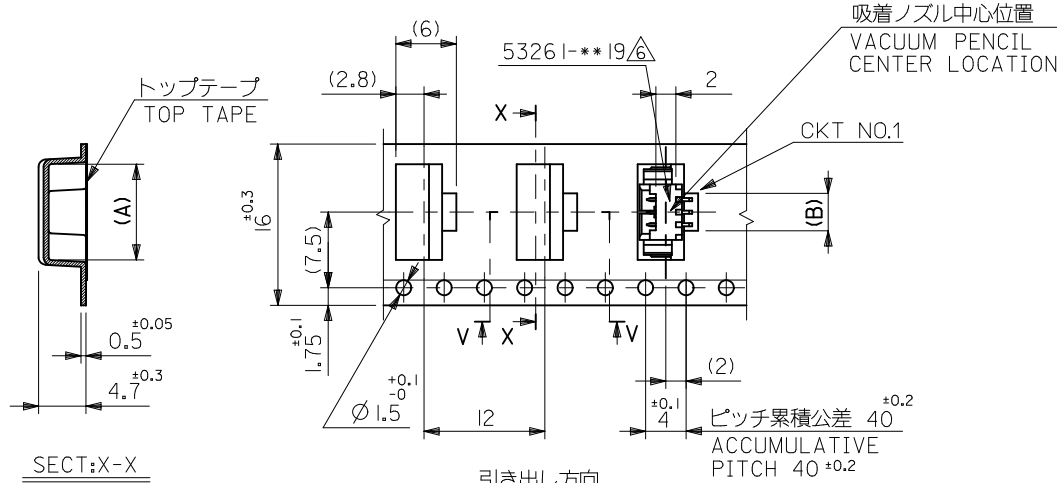
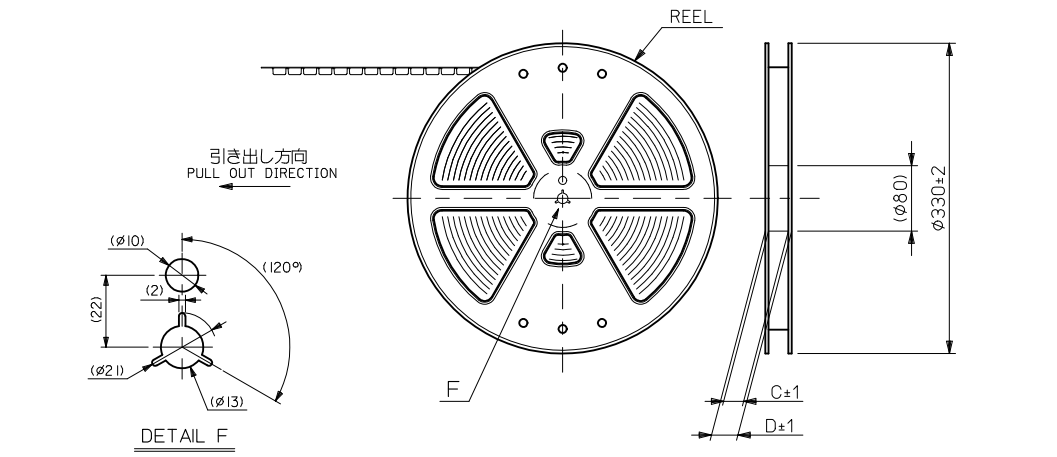
- 材料 (MATERIAL)
キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)
トップテープ (TOP TAPE): PET, PE, PEF
リール (REEL): ポリスチレン (PS) <リサイクル材含む>
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>

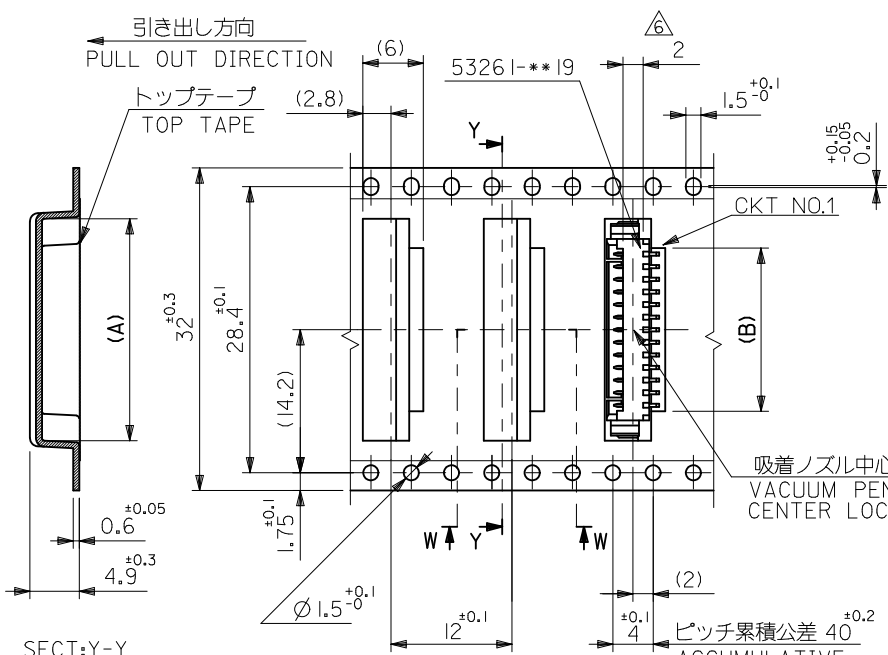
△ コネクタ、ハウジング平面部
CONNECTOR, HOUSING FLAT AREA

- 本製品は 53261-**-90 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53261-**-90
- ELV及びRoHS適合品
ELV AND RoHS COMPLIANT
- 本製品は乾燥剤入り、ハイバリア梱包仕様である。
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

16	21.4	17.4	3.7	9.5	53261-0371	3				
			2.45	8.25	53261-0271	2				
キャリアテープ幅 CARRIER TAPE WIDTH					D	C	B	A	EMBOSSD TAPE PACKAGE オーダー番号 ORDER NO.	極数 CKT.

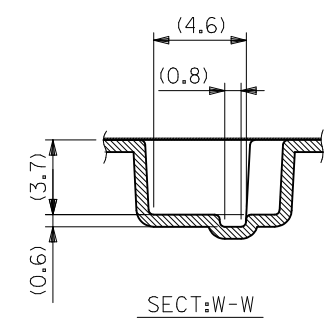
REVISED EC NO: D	DESCRIPTION 2010/02/17 DRWN: YGOTO CHKD: KASAKAWA APPR:	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC		THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY H. SHIMABUKUR	DATE '04/02/06	TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG					
		10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE '04/02/06	APPROVED BY NUKITA 2010/02/18					
		30 OVER	±0.3	MATERIAL NO. SEE TABLE & SHEET 2,3		DOCUMENT NO. SD-53261-023		SHEET NO. 1 OF 3			
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



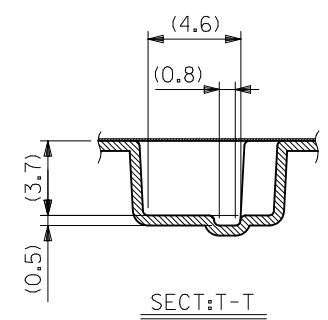


SECT:Y-Y

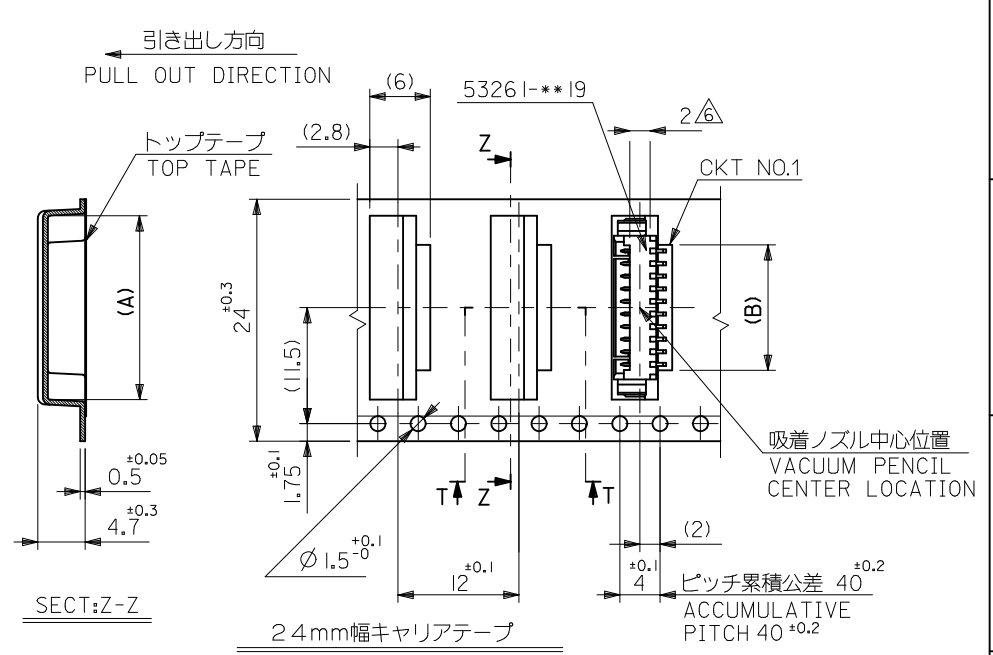
32mm幅キャリアテープ
32mm WIDTH CARRIER TAPE



SECT:W-W



SECT:T-T



SECT:Z-Z

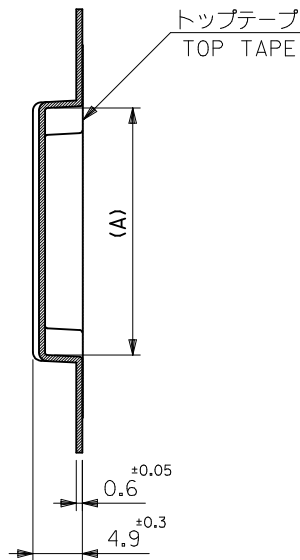
24mm幅キャリアテープ
24mm WIDTH CARRIER TAPE

32	37.4	33.4	16.2	22	53261-1371	13
			14.95	20.75	-1271	12
			13.7	19.5	-1171	11
			12.45	18.25	-1071	10
24	29.4	25.4	11.2	17	-0971	9
			9.95	15.75	-0871	8
			8.7	14.5	-0771	7
			7.45	13.25	-0671	6
			6.2	12	-0571	5
			4.95	10.75	53261-0471	4

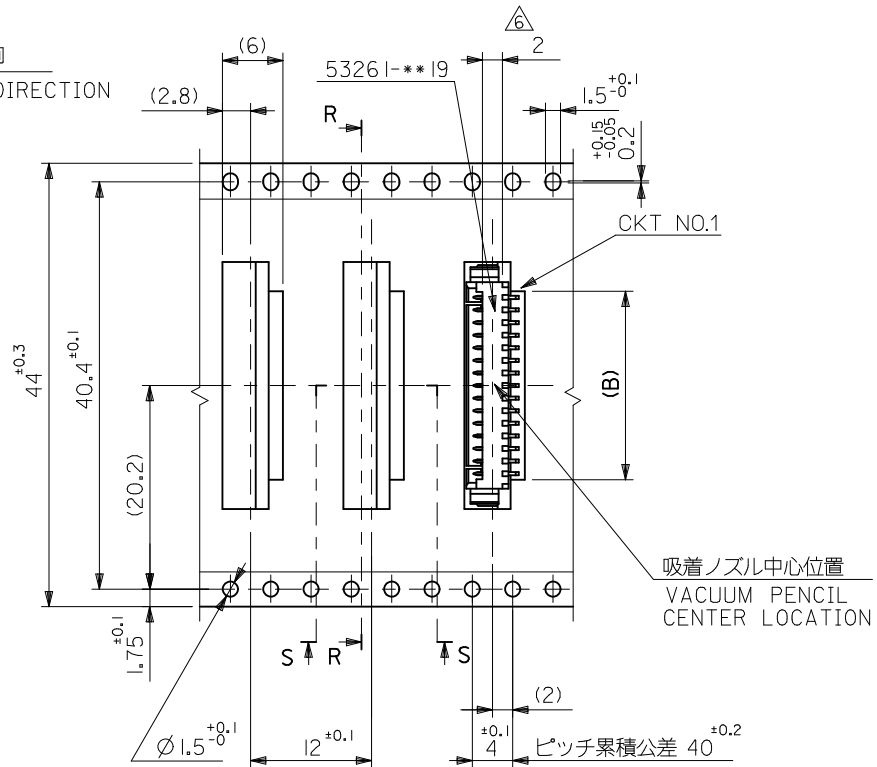
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	EMBOSSD TAPE PACKAGE	極数 CKT.
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MODEL NO.	53261-***71	DIMENSION STYLE	MM ONLY	SCALE	DESIGN UNITS	METRIC	THIRD ANGLE PROJECTION
REVISED	2010/02/17	GENERAL TOLERANCES (UNLESS SPECIFIED)	DRAWN BY	DATE	TITLE		
EC NO.	D	10 UNDER ±0.2	H. SHIMABUKUR	'04/02/06	1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG		
DRWN:	YG010	10 OVER 30 UNDER ±0.25	CHECKED BY	DATE	MOLEX INCORPORATED		
CHKD:	KASAKAWA	30 OVER ±0.3	K. TOJO	'04/02/06	SD-53261-023		
APPR:		ANGULAR ±3 °	APPROVED BY	DATE	DOCUMENT NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	NUKITA	2010/02/18	SHEET NO.		
			MATERIAL NO.	SEE TABLE & SHEET 1.3	2 OF 3		
			SIZE	A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

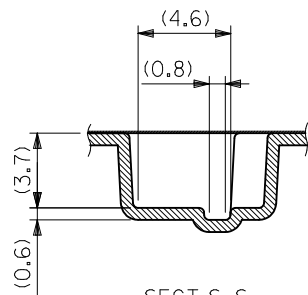
引き出し方向
PULL OUT DIRECTION



SECT:R-R



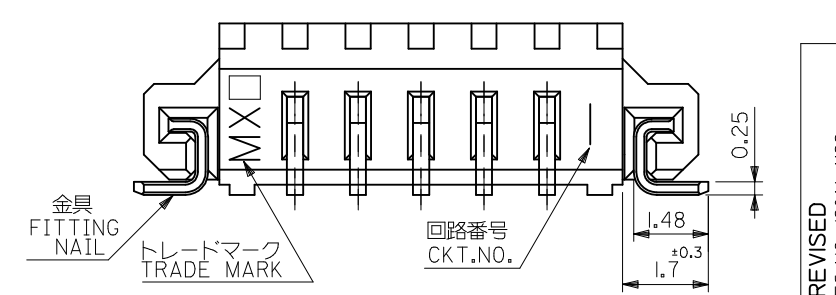
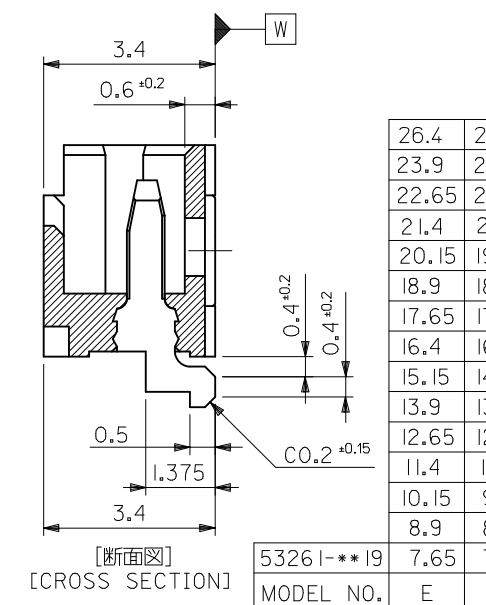
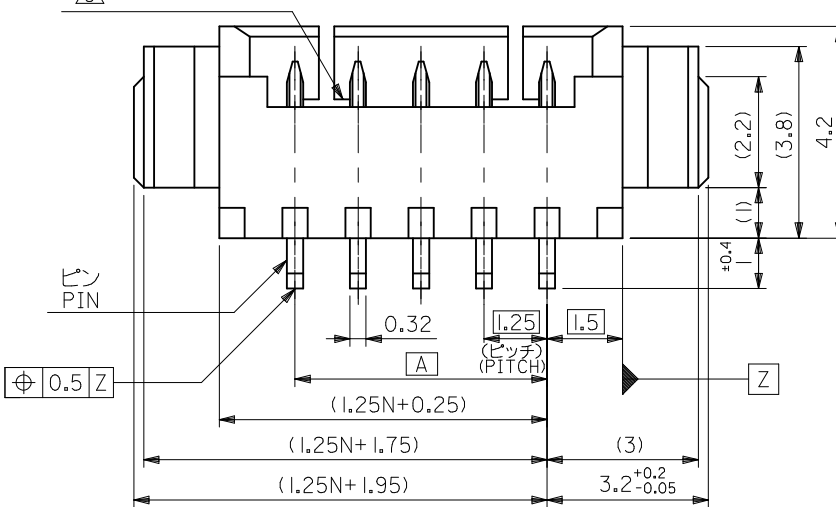
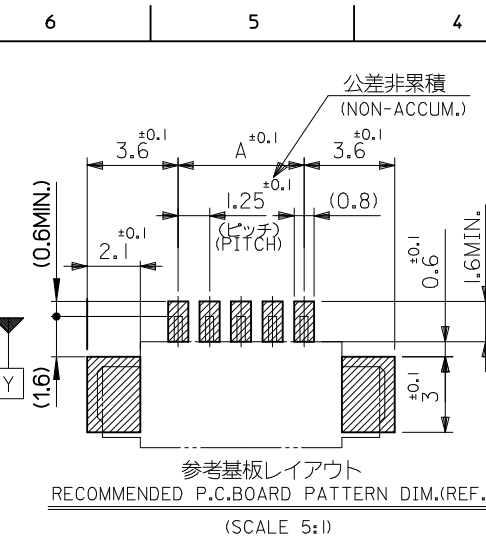
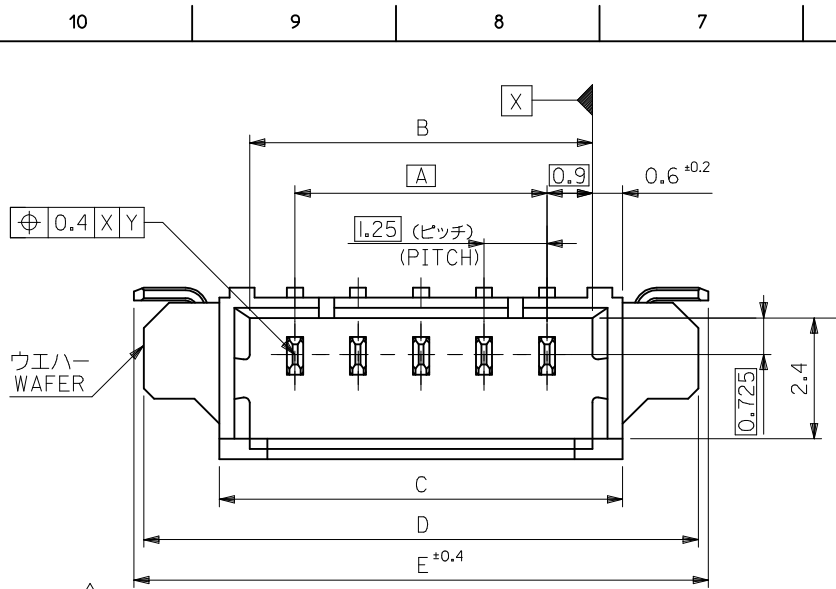
44mm幅キャリアテープ
44mm WIDTH CARRIER TAPE



SECT:S-S

44	49.4	45.4	18.7	24.5	53261-1571	15				
			17.45	23.25	53261-1471	14				
キャリアテープ幅 CARRIER TAPE WIDTH					D	C	B	A	EMBOSSD TAPE PACKAGE	極数 CKT.
MODEL NO. 53261-***71					ORDER NO.		オーダー番号			

REVISED EC NO: D	DESCRIPTION 2010/02/17 DRWN:YGOTO CHKD:KASAKAWA APPR:	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY H. SHIMABUKUR	DATE '04/02/06	TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG				
		10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE '04/02/06					
		30 OVER	±0.3	APPROVED BY NUKITA	DATE 2010/02/18	MATERIAL NO. SEE TABLE & SHEET 12		DOCUMENT NO. SD-53261-023		SHEET NO. 3 OF 3
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE & SHEET 12						



注記 NOTES

- 嵌合相手: 51021 シリーズ
MATES WITH: 51021 SERIES
- 材質 MATERIAL
ウエハー: NYLON46, UL94V-0
ピン: リン青銅
: PHOS-BRO
: 銅メッキ 1.0 マイクロメートル以上
: TIN 1.0 MICROMETER MINIMUM
: ニッケル下地 1.0 マイクロメートル以上
: NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM
金具
FITTING NAIL: リン青銅
: PHOS-BRO
: 銅メッキ 1.0 マイクロメートル以上
: TIN 1.0 MICROMETER MINIMUM
: ニッケル下地 1.0 マイクロメートル以上
: NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM
- ロック窓は2、3極は1箇所、4極以上は2箇所とする。
LOCKING WINDOW: ONE PLACE FOR 2 AND 3 CKT. AND TWO PLACES FOR MORE THAN 3 CKT.
- ソリダータール部のズレ量及び金具(補強板)のズレ量は基準面 W に対し、上方向 0.05MAX.、下方向に 0.1 MAX. とする。
OFFSET BETWEEN BASIS PLANE W TO SOLDER TAIL BOTTOM AND FITTING NAIL BOTTOM:
UPPER SIDE: 0.05MAX.
LOWER SIDE: 0.1MAX.
- 本製品は 53261-**-10 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53261-**10
- ELV及びRoHS適合品
ELV AND RoHS COMPLIANT.
- ソルダータール及び金具の平坦度は0.1以下。
SOLDER TAIL & FITTING NAIL COPLANARITY TO BE 0.1 MAX.

26.4	26	23	21.8	20	53261-1771	53261-1719	17	
23.9	23.5	20.5	19.3	17.5	-1571	-1519	15	
22.65	22.25	19.25	18.05	16.25	-1471	-1419	14	
21.4	21	18	16.8	15	-1371	-1319	13	
20.15	19.75	16.75	15.55	13.75	-1271	-1219	12	
18.9	18.5	15.5	14.3	12.5	-1171	-1119	11	
17.65	17.25	14.25	13.05	11.25	-1071	-1019	10	
16.4	16	13	11.8	10	-0971	-0919	9	
15.15	14.75	11.75	10.55	8.75	-0871	-0819	8	
13.9	13.5	10.5	9.3	7.5	-0771	-0719	7	
12.65	12.25	9.25	8.05	6.25	-0671	-0619	6	
11.4	11	8	6.8	5	-0571	-0519	5	
10.15	9.75	6.75	5.55	3.75	-0471	-0419	4	
8.9	8.5	5.5	4.3	2.5	-0371	-0319	3	
53261-**-19	7.65	7.25	4.25	3.05	1.25	53261-0271	53261-0219	2
MODEL NO.	E	D	C	B	A	EMBOSSED TAPE PKG ORDER No.	MATERIAL NO.	極数 CKT.

REVISED EC NO: J2016-1122 DRWN: QHEJ1 CHKD: SAKIYAMA APPR: IKANEKO 2016/04/26 2016/05/06 2016/05/06	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY HSHIMABU	DATE 04/02/06	TITLE 1.25 WIRE TO BOARD WAFER ASS FOR SMT	
0.25 OVER	0.5 UNDER	±0.05	CHECKED BY KTOJO	DATE 04/02/06			
0.5 OVER	1.0 UNDER	±0.1	APPROVED BY MSASAO	DATE 04/02/06			
1.0 OVER	10 UNDER	±0.2	MATERIAL NO.	DOCUMENT NO.	SEE CHART	SD-53261-024	SHEET NO. 1 OF 1
10 OVER	30 UNDER	±0.25	SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
30 OVER		±0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				